03/25/2015 503235561 PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:		NEW ASSIGN	NEW ASSIGNMENT				
NATURE OF CONVEYANCE:		ASSIGNMENT	ASSIGNMENT				
CONVEYING PARTY	DATA						
		Name			Execution Date		
DAISUKE SOHMA					03/31/2000		
TAKAHIRO ROPPON	GI				03/31/2000		
RECEIVING PARTY I	DATA						
Name:	SENJU	SENJU METAL INDUSTRY CO., LTD.					
Street Address:	23, SE	23, SENJU-HASHIDO-CHO					
City:	ADAC	ADACHI-KU, TOKYO					
State/Country:	JAPAN	JAPAN					
Postal Code:	120-85	120-8555					
Application Number		12916902					
Fax Number:	DATA	(412)945-5933					
Correspondence will	l be sent t	、 ,	first: if that is un	succes	sful. it will be sent		
using a fax number,		d; if that is unsucces			,		
Phone:		4124718815					
0		THE WEBB LAW FI	nments@webblaw.com				
•			GATEWAY CTR., 420 FT. DUQUESNE BLVD.				
Address Line 1:		SUITE 1200					
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ATTORNEY DOCKET	NUMBER:	0149-103319	0149-103319				
NAME OF SUBMITTE	R:	JULIE W. MED	JULIE W. MEDER				
SIGNATURE:		/Julie W. Mede	/Julie W. Meder/				
DATE SIGNED:		03/25/2015	03/25/2015				
Fotal Attachments: 3		I					
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U.S. DEPARTMENT OF COMMERCE United States Patent and Trademark Office

RECORDATION FORM COVER SHEET PATENTS ONLY						
To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.						
1. Name of conveying party(ies) Daisuke Sohma Takahiro Roppongi	2. Name and address of receiving party(ies) Name: SENJU METAL INDUSTRY CO., LTD. Internal Address:					
Additional name(s) of conveying party(ies) attached? Yes V No 3. Nature of conveyance/Execution Date(s): Execution Date(s) March 31, 2000 V Assignment Merger Security Agreement Change of Name Joint Research Agreement Government Interest Assignment Executive Order 9424, Confirmatory License Other	Street Address: 23, Senju-Hashido-cho City: Adachi-ku, Tokyo State: Country: JAPAN Zip: 120-8555 Additional name(s) & address(es) attached? Yes V No					
A. Patent Application No.(s) 12/916,902	document is being filed together with a new application. B. Patent No.(s)					
5. Name and address to whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:					
Name: Internal Address:_The Webb Law Firm	7. Total fee (37 CFR 1.21(h) & 3.41) \$ Authorized to be charged by credit card Authorized to be charged to deposit account					
Street Address: <u>One Gateway Center</u> 420 Ft. Duquesne Blvd., Ste 1200	 Enclosed None required (government interest not affecting title) 					
City: <u>Pittsburgh</u>	8. Payment Information					
State: <u>PA</u> Zip: <u>15222</u>	a. Credit Card Last 4 Numbers <u>1916</u> Expiration Date <u>05/2015</u>					
Phone Number: <u>412-471-8815</u> Fax Number: <u>412-945-5933</u> Email Address: <u>assignments@webblaw.com</u>	b. Deposit Account Number <u>23-0650</u> Authorized User Name					
9. Signature: Julie W. Meder Name of Person Signing	March 25, 2015 Date Total number of pages including cover sheet, attachments, and documents:					

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Doc. No. 3343124

ASSIGNMENT

WHEREAS, We, Daisuke SOHMA	•
and <u>Takahiro</u> ROPPONGI	residing
in <u>B-201, 1539, Hiqashiqo, Mohka-shi, Tochiqi, Japan</u>	and
A-201, 831-3, Hiramatsuhoncho, Utsunomiya-shi, Tochigi, Japan, resp	pectively,
have invented certain new and useful improvements	entitled
COATED SOLDER SPHERES AND METHOD FOR PRODUCING THE SAME	
for which we have this day executed an application f	or United
States Letters Patent;	·
AND, WHEREAS SENIL METAL INDUSTRY CO. ITD	-

corporation of <u>Japan</u>, having a place of business at <u>23</u>, <u>Senju-Hashido-cho</u>, <u>Adachi-ku</u>, <u>Tokyo</u>, <u>Japan</u>, hereinafter called the "assignee", is desirous of acquiring the entire right, title, and interest in and to said application and the inventions and improvements therein disclosed.

NOW, THEREFORE, in consideration of One (\$1.00) Dollar and other good and valuable consideration paid to us by said assignee, the receipt of which is hereby acknowledged, we do hereby assign, sell, transfer, and set over unto said assignee the entire right, title and interest in and to said application and the inventions and improvements therein disclosed for the United States and all foreign countries and any Letters Patent which may issue therefor in the United States and all foreign countries and all divisions, reissues, continuations, renewals, and/or extensions thereof, said assignee to have and to hold the interests herein assigned to the full ends of the terms of said Letters Patent and any and all divisions, reissues, continuations, renewals, and/or extensions thereof, respectively, as fully and entirely as the same would have been held and enjoyed by us had this assignment not been made.

The Commissioner of Patents and Trademarks is requested to issue such Letters Patent in accordance herewith. We covenant that we are the lawful owners of the said application, inventions, and improvements, that the same are unencumbered, that no license has been granted to make, use, or vend the said inventions or improvements or any of them, and that we have the full right to make this assignment.

And for the consideration aforesaid, we agree jointly and individually that we will communicate to said assignee or the representatives thereof any facts known to us respecting said inventions and improvements, and will, upon request, but without expense to us, testify in any legal proceedings, sign all lawful papers, execute all divisional, reissue, continuation, renewal, and/or extension applications, make all rightful oaths, and generally do all other and further lawful acts, deemed necessary or expedient by said assignee or by counsel for said assignee, to assist or enable said assignee to obtain and enforce full benefits from the rights and interests herein assigned. This assignment shall be binding upon our heirs, executors,

administrators, and/or assigns, and shall inure to the benefit of the heirs, executors, administrators, successors, and/or assigns, as the case may be, of said assignee.

Dated: March 31, 2000

Daisuke Jakahiro Daisuke SOHMA

Dated: March 31, 2000

Roppongi Takahiro ROPPONGI

PATENT REEL: 035255 FRAME: 0143

RECORDED: 03/25/2015